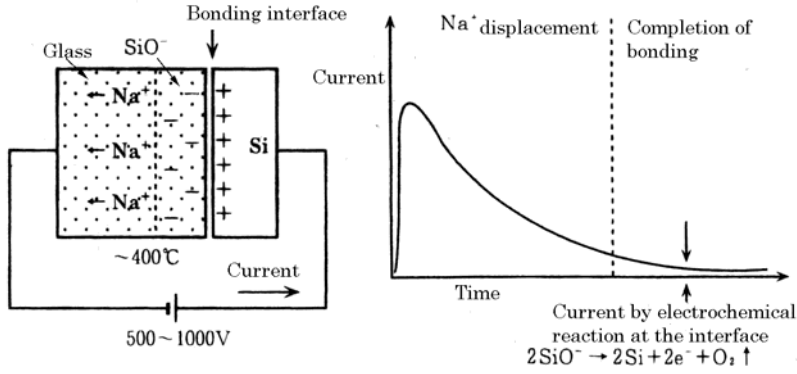
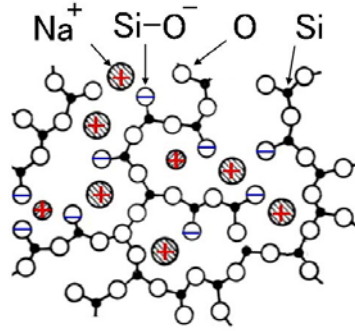


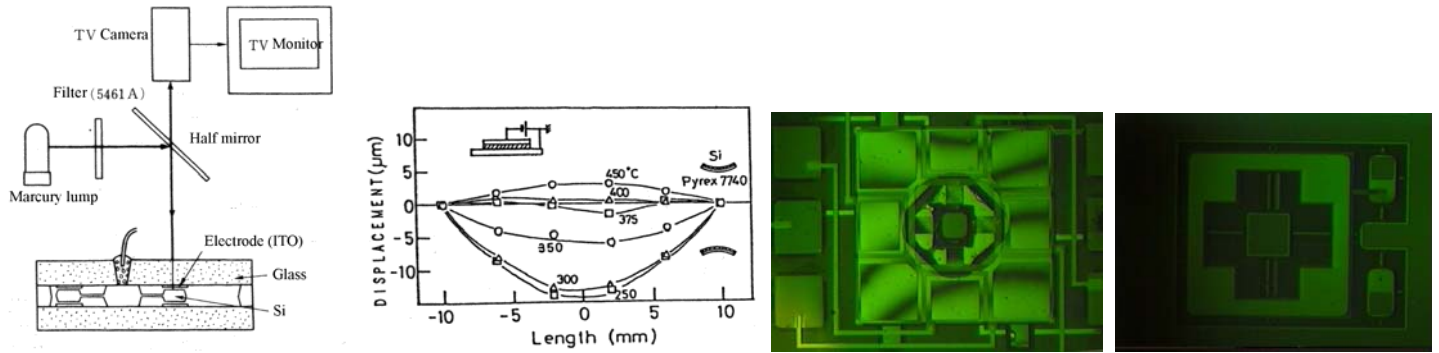
Anodic Bonding



Principle of anodic bonding

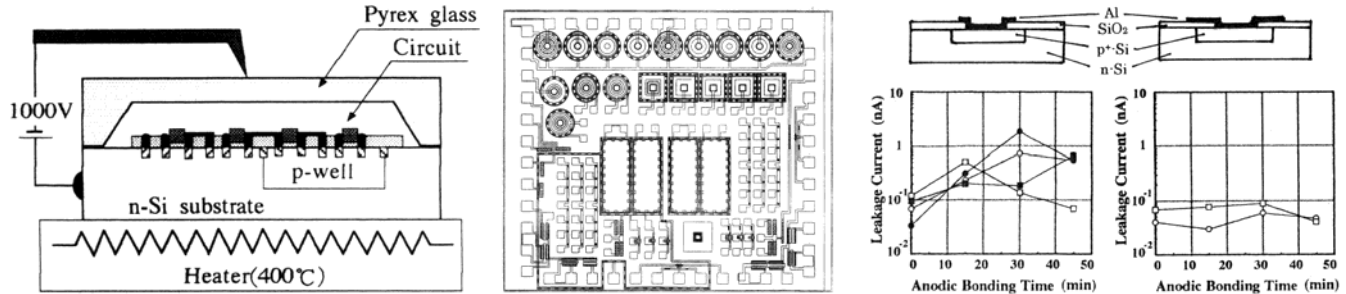


Molecular structure of glass



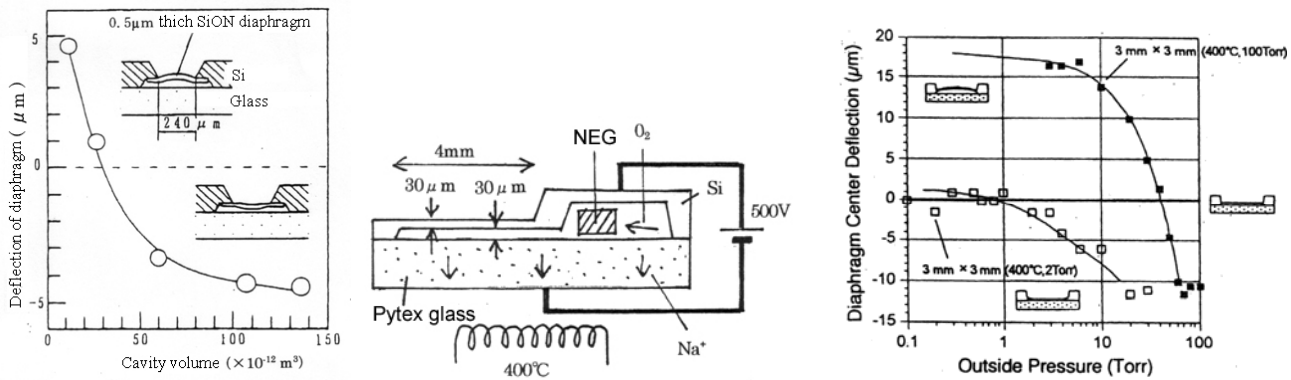
Distortion after anodic bonding

Reference : Y.Shoji, K.Minami, M.Esashi, Glass-silicon Anodic Bonding for the Reduction of Structural Distortion, Trans. IEE of Japan, 115-A (1995) pp.1208-1213



Influences of anodic bonding to CMOS circuit

Reference : M.Shirai, M.Esashi, Circuit Damage by Anodic Bonding, Technical Report IEE of Japan, ST-92-7 (1992) pp.9-17



Vacuum packaging and pressure controlled packaging (right) by anodic bonding

Reference : N.Ura, K.Nakaichi, K.Minami, M.Esashi, Vacuum Packaging by Anodic Bonding, The 11th Sensor Symposium (1992) p.63

M.Esashi, Vacuum Packaging Technology for Microsensors, Trans. IEE of Japan, 120-E (2000) pp.310-314